



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q65445

Hiroshi SUMI, et al.

Appln. No.: 09/904,097

Group Art Unit: 2827

Confirmation No.: 1333

Examiner: Jose H. Alcala

Filed: July 13, 2001

For: PASTE FOR FILLING THROUGH HOLE AND PRINTED WIRING BOARD USING
SAME

REQUEST FOR APPROVAL OF PROPOSED DRAWING CORRECTIONS

Commissioner for Patents
Washington, D.C. 20231

Sir:

Submitted herewith please find 7 sheet(s) of proposed drawing corrections with the changes described below and highlighted in the proposed drawing corrections. Of the original twenty-one figures, all of them have been modified in the proposed drawing corrections except for Fig. 1. The proposed drawing corrections have been highlighted instead of marked with red ink to more clearly illustrate the changes, primarily in crosshatching, without adding confusion to their appearance. Furthermore, the highlighting was applied only in the first proposed drawing correction in which the correction was made although the proposed drawing corrections for each corrected element were made consistent throughout any subsequent figures. The Examiner is respectfully requested to acknowledge receipt of the drawing corrections and to approve the changes.

In corrected Figs. 2-6, element 2 is a substrate now reflected with crosshatching for plastic.

REQUEST FOR APPROVAL OF
PROPOSED DRAWING CORRECTIONS
U.S. Application No.: 09/904,097

Element 4 is conductor layer now reflected with crosshatching for a semi-conductor.

Element 6 is a hydrophobic surface now reflected with crosshatching for stipple.

Element 10 is a cured throughhole filling material now reflected with crosshatching for an adhesive.

In corrected Fig. 7, elements 101, 190 and 400 are insulating substrates or layers now reflected with crosshatching for a section of electrical insulation.

Element 102 is a throughhole filling paste now reflected with crosshatching for an adhesive.

Element 130 is a chip capacitor now reflected with crosshatching for synthetic resin.

Element 140 is an electrode now reflected with crosshatching for a metal.

Element 150 is a laminate wherein an insulating layer and a conductor are alternately formed now reflected with crosshatching for a semi-conductor.

Element 160 is an imbedding resin now reflected with crosshatching for a synthetic resin.

Element 170 is a cover pad now reflected with crosshatching for a metal.

Element 200 is a terminal electrode of copper foil now reflected with crosshatching for a metal.

Elements 210 and 240 are solder resist layers now reflected with crosshatching for a synthetic resin.

Element 230 is wiring now reflected with crosshatching for a metal.

Element 280 is a semiconductor die now reflected with crosshatching for a section of packed silicon.

REQUEST FOR APPROVAL OF
PROPOSED DRAWING CORRECTIONS
U.S. Application No.: 09/904,097

Element 290 is a connecting pad now reflected with crosshatching for a metal.

Element 300 is underfill material now reflected with crosshatching for stipple.

Element 700 is a copper panel deposit now reflected with crosshatching for a metal.

Element 800 is a via hole conductor now reflected with crosshatching for a metal.

Element 900 is a throughhole conductor now reflected with crosshatching for a metal.

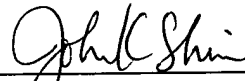
Corrected Figs. 8-21 have been updated to reflect the crosshatching of the elements consistent with corrected Fig. 7.

In corrected Fig. 9, element 300 was changed to 301 in response to the Examiner's objection.

In corrected Fig. 14, element 120 is masking tape now reflected with crosshatching for an adhesive.

No new matter is added. Applicants respectfully request approval of the attached corrected drawings.

Respectfully submitted,



John K. Shin
Registration No. 48,409

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE



23373

PATENT TRADEMARK OFFICE

Date: April 2, 2003